

#### **FEATURES**

- Operates From 1.65 V to 3.6 V
- Max t<sub>pd</sub> of 2.8 ns at 3.3 V
- ±24-mA Output Drive at 3.3 V
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

## DESCRIPTION/ORDERING INFORMATION

This quadruple 2-input positive-OR gate is designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

The SN74ALVC32 performs the Boolean function  $Y = \overline{\overline{A} \cdot \overline{B}}$  or Y = A + B in positive logic.

#### **ORDERING INFORMATION**

T <sub>A</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SOIC - D	Tube	SN74ALVC32D	ALVC32
	3010 - 0	Tape and reel	SN74ALVC32DR	ALV032
-40°C to 85°C	SOP - NS	Tape and reel	SN74ALVC32NSR	ALVC32
-40°C 10 85°C	TSSOP - PW	Tube	SN74ALVC32PW	VA32
	1330P - PW	Tape and reel	SN74ALVC32PWR	VA3Z
	TVSOP - DGV	Tape and reel	SN74ALVC32DGVR	VA32

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

# FUNCTION TABLE (each gate)

INPU	JTS	OUTPUT			
Α	в	Y			
Н	Х	Н			
Х	Н	Н			
L	L	L			

#### LOGIC DIAGRAM, EACH GATE (POSITIVE LOGIC)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

1A [ 1B ] 1Y ] 2A ] 2B ] 2Y ] GND ]	1 2 3 4 5 6 7	σ	14 13 12 11 10 9 8		V <sub>CC</sub> 4B 4A 4Y 3B 3A 3Y	<i></i>
GND [	7		8	μ	3Y	



#### **ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range		-0.5	4.6	V
VI	Input voltage range <sup>(2)</sup>		-0.5	4.6	V
Vo	Output voltage range <sup>(2)(3)</sup>		-0.5	$V_{CC} + 0.5$	V
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
lo	Continuous output current			±50	mA
	Continuous current through $V_{CC}$ or GND			±100	mA
		D package		86	
0	Package thermal impedance <sup>(4)</sup>	DGV package		127	0000
$\theta_{JA}$		NS package		76	°C/W
		PW package		113	
T <sub>stg</sub>	Storage temperature range	·	-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) This value is limited to 4.6 V maximum.

(2)

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

#### **RECOMMENDED OPERATING CONDITIONS**<sup>(1)</sup>

			MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage		1.65	3.6	V	
		V <sub>CC</sub> = 1.65 V to 1.95 V	$0.65  imes V_{CC}$			
VIH	High-level input voltage	$V_{CC}$ = 2.3 V to 2.7 V	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
	/ <sub>IL</sub> Low-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V		$0.35\times V_{CC}$		
V <sub>IL</sub>		$V_{CC}$ = 2.3 V to 2.7 V		0.7	V	
		$V_{CC} = 2.7 V \text{ to } 3.6 V$		0.8		
VI	Input voltage		0	3.6	V	
Vo	Output voltage		0	V <sub>CC</sub>	V	
		V <sub>CC</sub> = 1.65 V		-4		
	High-level output current	V <sub>CC</sub> = 2.3 V		-12	2	
I <sub>OH</sub>		V <sub>CC</sub> = 2.7 V		-12	mA	
		V <sub>CC</sub> = 3 V		-24		
		V <sub>CC</sub> = 1.65 V		4		
		V <sub>CC</sub> = 2.3 V		12	1.	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2.7 V		12	mA	
		V <sub>CC</sub> = 3 V		24		
$\Delta t / \Delta v$	Input transition rise or fall rate			5	ns/V	
T <sub>A</sub>	Operating free-air temperature		-40	85	°C	

 All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

#### **ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
	I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2			
	I <sub>OH</sub> = -4 mA	1.65 V	1.2			
	I <sub>OH</sub> = -6 mA	2.3 V	2			
V <sub>OH</sub>		2.3 V	1.7			V
	I <sub>OH</sub> = -12 mA	2.7 V	2.2			
		3 V	2.4			
	I <sub>OH</sub> = -24 mA	3 V	2			
	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V			0.2	
	I <sub>OL</sub> = 4 mA	1.65 V			0.45	
N/	I <sub>OL</sub> = 6 mA	2.3 V			0.4	V
V <sub>OL</sub>	1. 10 1	2.3 V			0.7	v
	I <sub>OL</sub> = 12 mA	2.7 V			0.4	
	I <sub>OL</sub> = 24 mA	3 V			0.55	
I <sub>I</sub>	$V_{I} = V_{CC}$ or GND	3.6 V			±5	μA
I <sub>CC</sub>	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	3.6 V			10	μA
$\Delta I_{CC}$	One input at $V_{CC}$ - 0.6 V, Other inputs at $V_{CC}$ or GND	3 V to 3.6 V			750	μA
Ci	$V_{I} = V_{CC} \text{ or } GND$	3.3 V		4		pF

(1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

#### SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = ± 0.1	1.8 V 5 V	V <sub>CC</sub> = ± 0.		V <sub>CC</sub> =	2.7 V	V <sub>CC</sub> = 3 ± 0.3	3.3 V 3 V	UNIT
	(INFOT)	(001F01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A or B	Y	1	4.7	1	3.1		2.9	1	2.8	ns

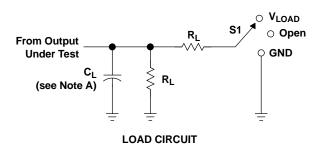
### **OPERATING CHARACTERISTICS**

 $T_A = 25^{\circ}C$ 

	PARAMETER		PARAMETER TEST CONDITIONS		$V_{CC}$ = 2.5 V ± 0.2 V	$V_{CC}$ = 3.3 V ± 0.3 V	UNIT
				TYP	TYP	TYP	
$C_{pd}$	Power dissipation capacitance per gate	$C_{L} = 0,$	f = 10 MHz	23	24	26	pF

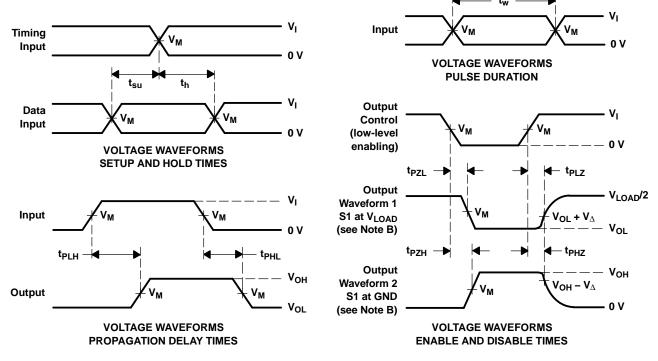


#### PARAMETER MEASUREMENT INFORMATION



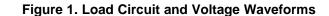
TEST	S1
t <sub>pd</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>LOAD</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

N N	IN	PUT	V	v	6	Р	V
V <sub>cc</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	C∟	RL	$V_{\Delta}$
1.8 V $\pm$ 0.15 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	$2 \times V_{CC}$	30 pF	<b>1 k</b> Ω	0.15 V
2.5 V $\pm$ 0.2 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	$2 \times V_{CC}$	30 pF	<b>500</b> Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	<b>500</b> Ω	0.3 V
3.3 V $\pm$ 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	<b>500</b> Ω	0.3 V



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω.
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.



## **MECHANICAL DATA**

PLASTIC SMALL-OUTLINE

MPDS006C - FEBRUARY 1996 - REVISED AUGUST 2000

#### DGV (R-PDSO-G\*\*)

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153

14/16/20/56 Pins – MO-194



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AB.



### MECHANICAL DATA

#### PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



## **MECHANICAL DATA**

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

# PW (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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